

No-Clean Flux Paste

8341 is designed for lead-free alloys, but also works well with conventional leaded solders. This tacky no-clean flux paste uses a mix of rosin, thickener, and high-grade synthetically refined resin. The flux provides fast and widespread wetting during soldering and leaves non-conductive and non-tacky residues.

This solder flux paste is ideal for solder touch-ups, repairs, or reworks of surface mount assemblies.

Read the product SDS before using this product (downloadable at www.mgchemicals.com).

Features & Benefits

- Soldering flux paste for electronics
- Excellent wettability
- Clear, non-conductive, and non-tacky residues
- Usable for both lead-free and leaded alloys
- Meets J-STD-004B
- RoHS-compliant

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
8341-10ML	Syringe	10 mL	9.80 g
8341-50ML	Jar	50 mL	49.0 g



Properties

Flux Classification	ROL1
Flux Type	Rosin
Flux Activity	Low
Copper Mirror	Pass
Corrosion	Pass
Flux Residue Dryness	Pass
Surface Insulation Resistance (SIR)	Pass
Electromigration (ECM)	
IR initial, 96 h	Pass
IR final, 596 h	Pass
Cleaning Requirements	Recommended
Acid Number (mgKOH/g sample)	126
Halides (by weight)	<0.5 %
Halogen Content	0.81 %

Application Instructions

1. Apply flux on the surface by manual or robotic dispensing application.
2. Clean residue with MG 413B, 413C, 4140, 4050A, or 4140A flux removers.

Storage and Handling

Store between 18 and 27 °C in a dry area, away from sunlight (see SDS).

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.